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DN 98:76868

TI Fine copper alloy wire with high strength and flexibility

PA Furukawa Electric Co., Ltd., Japan

SO Jpn. Kokai Tokkyo Koho, 4 pp.

Sn 0.11 and Ag 0.49%.

CODEN: JKXXAF

DT Patent

LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
ΡI	JP 57145954	<b>A</b> 2	19820909	JP 1981-32269	19810306
PRAI	JP 1981-32269		19810306		

AB The Cu alloys contain Sn 0.1-1, Ag 0.1-0.49, and optionally P, Zn, and/or Mn ≤0.2%. An ingot is scalped, hot worked, annealed at 550°, pickled, drawn 99.96% to 0.15 mm, and straightened. The yield strength is 77.2-80.3, tensile strength 87.9-89.7 kg/mm2, elec. conductivity 64.8-84.7% IACS, flexibility good, and drawability satisfactory, compared with 72.1, 74.3 kg/mm2, 30.8%, bad, and difficult to 89.8% for the conventional Cu alloy containing Ni 1.98 and Mn 0.48%. A typical Cu alloy [84506-98-9] contains